

**I. AMENDMENTS TO THE CLAIMS**

The following amendments are requested according to the revised format as set forth in 1267 OG 106 (Feb. 25, 2003). Deleted matter is indicated by strike-out text and added matter is indicated by underlined text.

Claims 1-6 (canceled)

Claim 7 (currently amended) An electroplating solution for plating tin-bismuth solder coatings comprising:

- a sulfonic acid electrolyte;
- a tin compound soluble in the electrolyte to form a tin sulfonate;
- a bismuth compound soluble in the electrolyte to form a bismuth sulfonate;
- a non-ionic surfactant comprising a polyethylene glycol-block-polypropylene glycol with a molecular weight between 2,000 and 10,000;
- a grain refiner; and
- an antioxidant.

Claim 8 (currently amended) The electroplating solution of claim 1 7 wherein the ~~non-ionic surfactant~~ polyethylene glycol-block-polypropylene glycol comprises ~~polyethylene~~ polyethylene glycol-ran-polypropylene glycol with a molecular weight between 2,000 and 10,000.

Claim 9 (currently amended) The electroplating solution of claim 1 7 wherein the ~~non-ionic surfactant~~ polyethylene glycol-block-polypropylene glycol comprises ethylenediamine tetrakis polyethylene glycol-block-polypropylene glycol tetrol with a molecular weight between 2,000 and 7,000.

Claim 10 (currently amended) The electroplating solution of claim 1 7 wherein the antioxidant comprises ~~polyhydroxybenzine~~ polyhydroxybenzene.

Claim 11 (currently amended) The electroplating solution of claim 1 7 wherein the grain refiner comprises an acrylic acid.